

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0541324362](#)
Status: **Active**
Overview: [ffc fpc smt](#)
Description: 0.50mm (.020") Pitch FFC/FPC Connector, Right Angle, SMT, ZIF, Bottom Contact Style, 43 Circuits, 0.1µm (4µ") Gold (Au) Contact Plating

Documents:

[3D Model](#) [Product Specification PS-54132-061 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

UL E29179

General

Product Family FFC/FPC Connectors
 Series [54132](#)
 Overview [ffc fpc smt](#)
 Product Name N/A

Physical

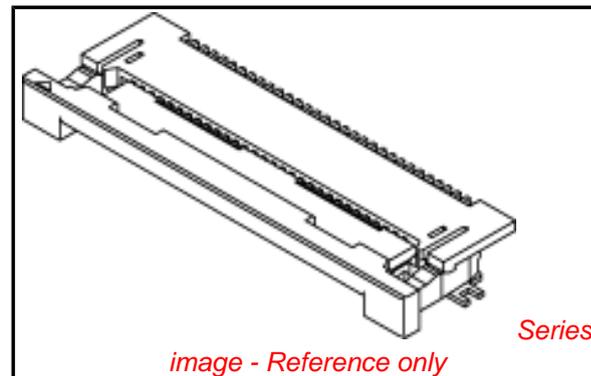
Circuits (Loaded) 43
 Color - Resin Black, Natural
 Contact Position Bottom
 Durability (mating cycles max) 20
 Entry Angle 90° Angle
 Flammability 94V-0
 Mated Height (in) 0.079 In
 Mated Height (mm) 2.00 mm
 Material - Metal Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Gold
 Material - Resin High Temperature Thermoplastic
 Number of Rows 1
 Orientation Right Angle
 PCB Locator No
 PCB Retention Yes
 Packaging Type Embossed Tape on Reel
 Pitch - Mating Interface (in) 0.020 In
 Pitch - Mating Interface (mm) 0.50 mm
 Plating min: Mating (µin) 4
 Plating min: Mating (µm) 0.1
 Plating min: Termination (µin) 2
 Plating min: Termination (µm) 0.05
 Polarized to PCB Yes
 Stackable No
 Surface Mount Compatible (SMC) N/A
 Temperature Range - Operating -20°C to +85°C
 Termination Interface: Style Surface Mount
 Wire/Cable Type FFC/FPC

Electrical

Current - Maximum per Contact 0.5A
 Voltage - Maximum 50V

Material Info

Reference - Drawing Numbers



EU RoHS

ELV and RoHS Compliant

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Halogen-Free

Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

China RoHS

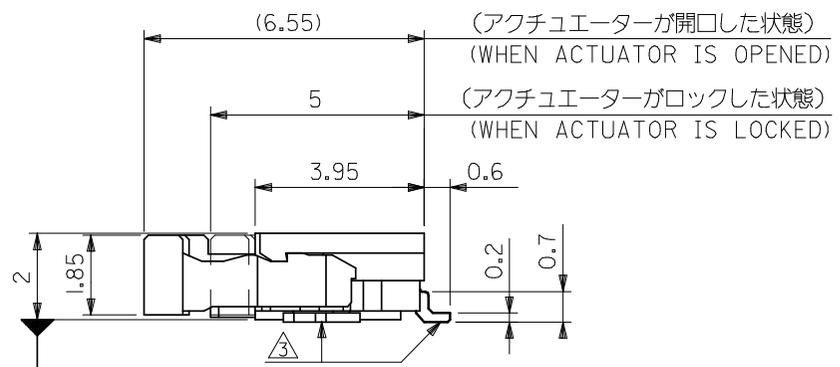
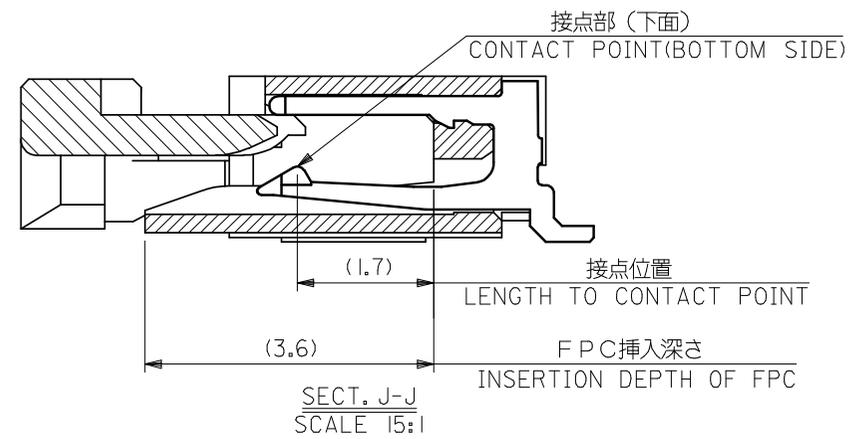
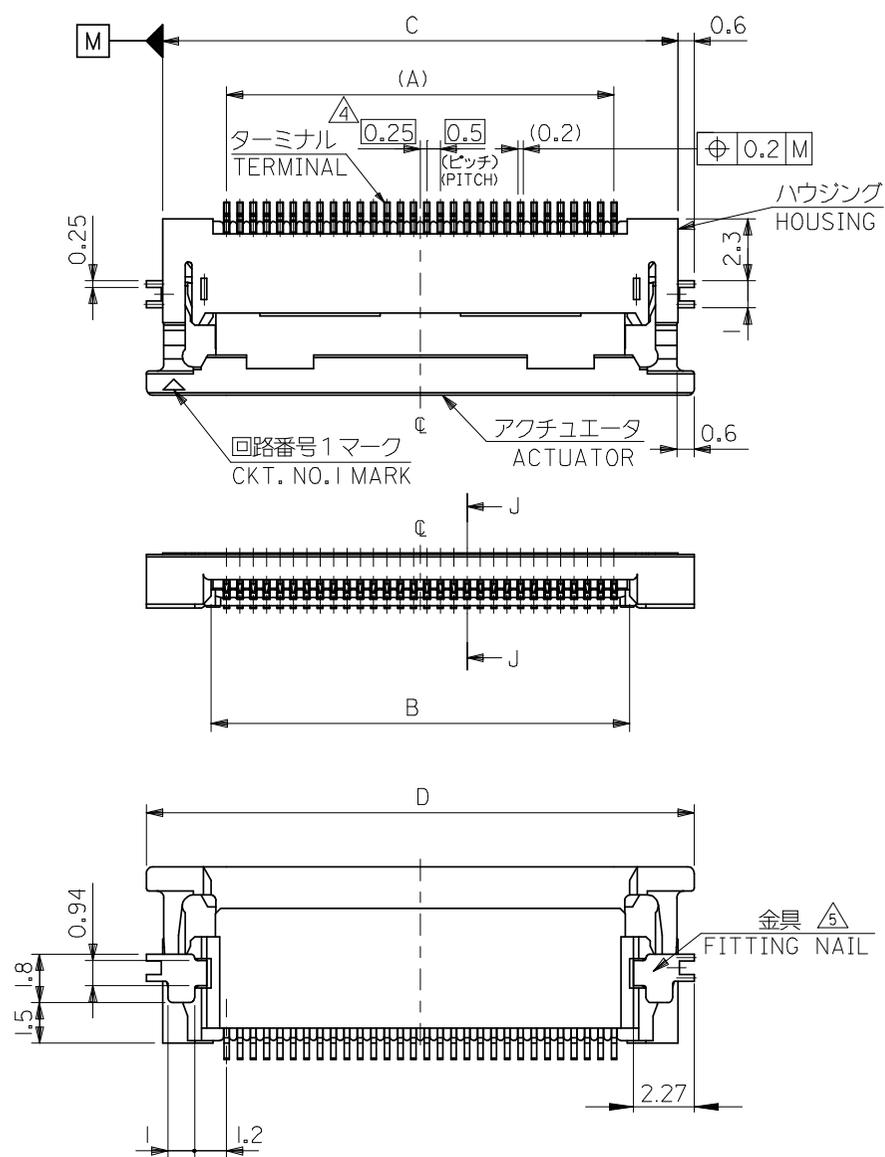


Search Parts in this Series

[54132Series](#)

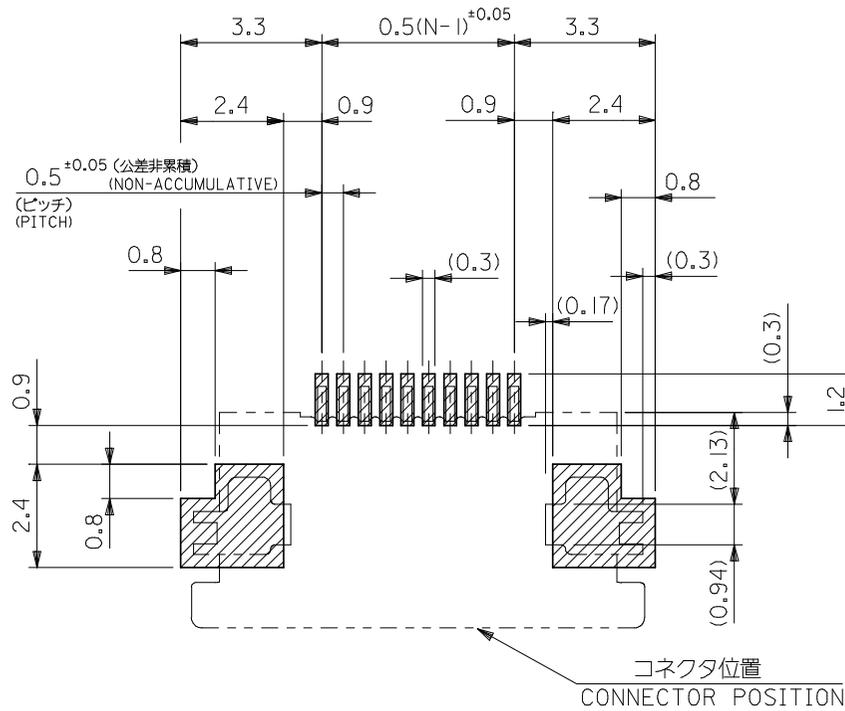
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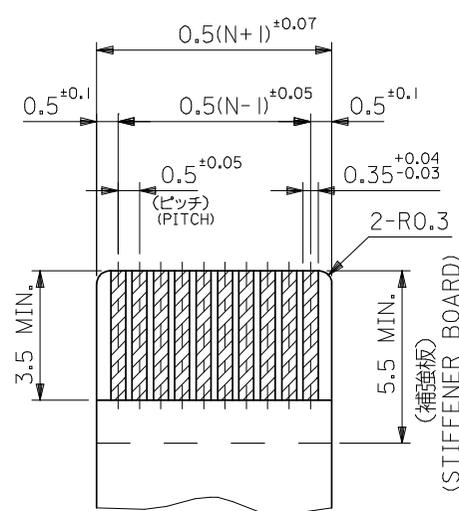


30.5	29.3	25.65	24.5	54132-5062	54132-5068	50
28.0	26.8	23.15	22.0	54132-4562	54132-4568	45
27.0	25.8	22.15	21.0	54132-4362	54132-4368	43
25.5	24.3	20.65	19.5	54132-4062	54132-4068	40
24.5	23.3	19.65	18.5	54132-3862	54132-3868	38
23.5	22.3	18.65	17.5	54132-3662	54132-3668	36
23.0	21.8	18.15	17.0	54132-3562	54132-3568	35
22.5	21.3	17.65	16.5	54132-3462	54132-3468	34
22.0	20.8	17.15	16.0	54132-3362	54132-3368	33
21.5	20.3	16.65	15.5	54132-3262	54132-3268	32
20.5	19.3	15.65	14.5	54132-3062	54132-3068	30
D	C	B	A	EMBOSSED TAPE		MATERIAL. NO.
				ORDER No. オーダー番号		CKT.

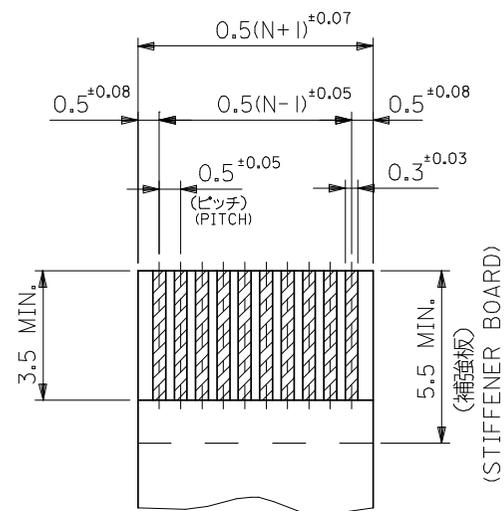
REVISED EC NO: J2008-4308 DRWN: WABEI 2008/06/27 CHKD: THARUYAMA 2008/06/30 APPR: NUKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)		
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2004/09/27	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2004/09/27	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
	ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	SD-54132-064	1 OF 4
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



参考基板レイアウト
RECOMMENDED PC BOARD PATTERN DIMENSION(REF.)
(マウント面)
(MOUNTING SIDE)



適用FPC推奨寸法
APPLICABLE FPC RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適用FFC推奨寸法
APPLICABLE FFC RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

注記
NOTES

1. 使用材料 MATERIAL : 46ナイロン, UL 94V-0 : 46NYLON
ハウジング HOUSING : PPS, UL 94V-0 : PPS
アクチュエーター ACTUATOR : 金メッキ
ターミナル TERMINAL : コンタクト部 0.1 MICRO METER MIN. テール部 0.05 MICRO METER MIN. ニッケル下地 1.0 MICRO METER MIN.
FITTING NAIL : GOLD PLATING CONTACT PORTION: 0.1 MICRO METER MIN. TAIL PORTION: 0.05 MICRO METER MIN. NI-PLATING: 0.1 MICRO METER MIN.
金具 : リン青銅 (t=0.2)、鍍メッキ 1.0~3.0 MICRO METER MIN. ニッケル下地 1.0~3.0 MICRO METER MIN. PHOS-BRO, TIN-PLATE 1.0~3.0 MICRO METER MIN. OVER NICKEL 1.0~3.0 MICRO METER MIN.

2. エンボステーブ梱包時は、アクチュエーターがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54132-**69 SHOULD BE LOCKED.
3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 田に対し上方向0.1MAX、下方向0.15MAXとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAIL FROM 田 UPPER DIRECTION: 0.1 MAX., LOWER DIRECTION: 0.15 MAX.
4. 偶数極に適用
APPLY FOR EVEN CIRCUIT.
5. パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
6. 本製品は54132-**61に対するニッケルバリア品である。
THIS PRODUCT IS Ni-BARRIER OF 54132-**61.

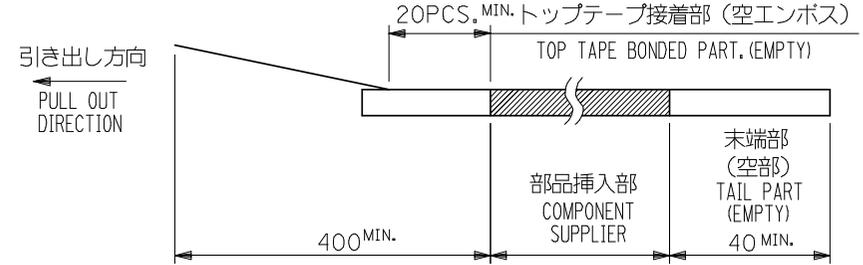
FPC/FFCについて:
打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートル
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC:
THICKNESS OF SOFT COPPER FOIL : 35 micrometer or 50 micrometer

FPCについて:
補強フィルム材質はポリイミドを推奨いたします。
接着剤は熱硬化接着剤を推奨いたします。
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

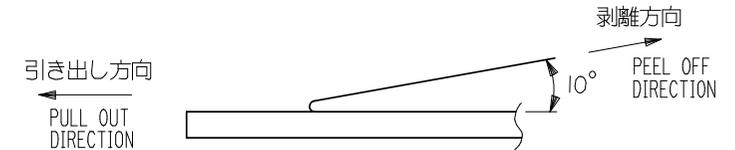
REVISED EC NO: J2008-4308 DRWN: MWABEI CHKD: THARUYAMA APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)	
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2004/09/27	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2004/09/27	DOCUMENT NO. SD-54132-064	SHEET NO. 2 OF 4
	ANGULAR	±3 °	MATERIAL NO. SEE SHEET 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

NOTES

1. 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



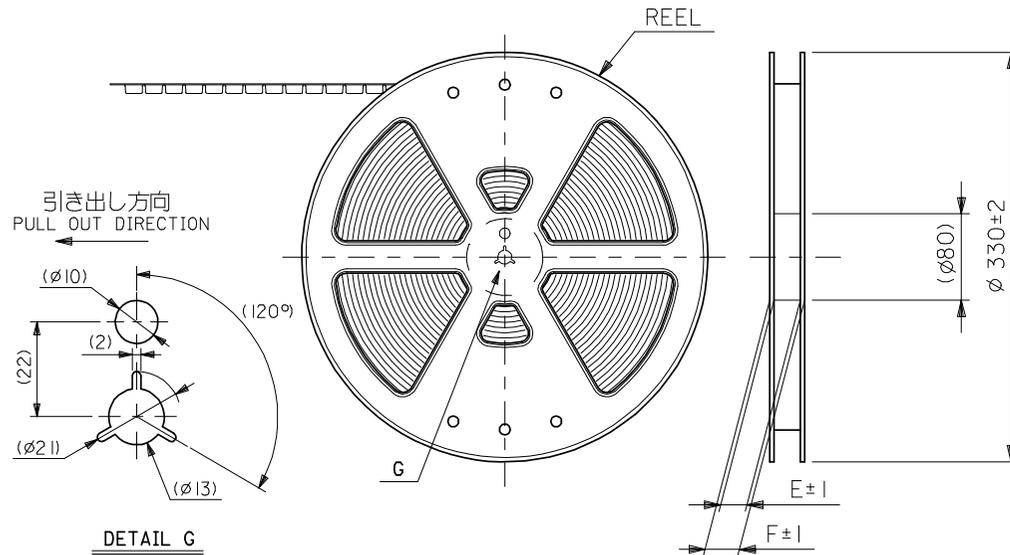
3. トップテープの剥離強度：0.1N ~ 1.3N (10gf ~ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 1.3N (10gf ~ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



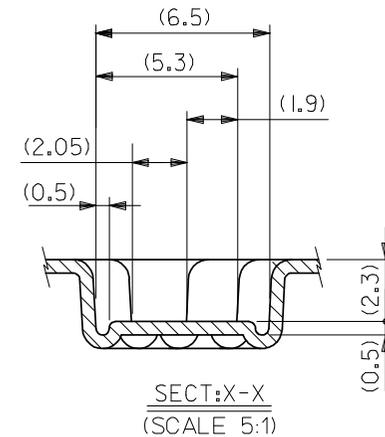
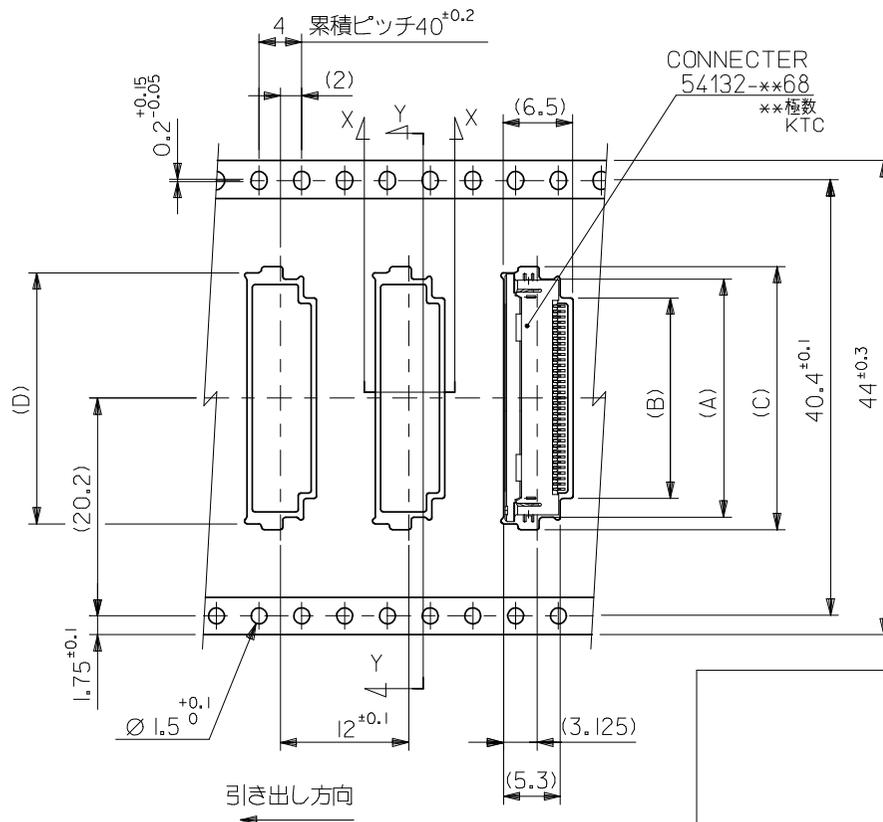
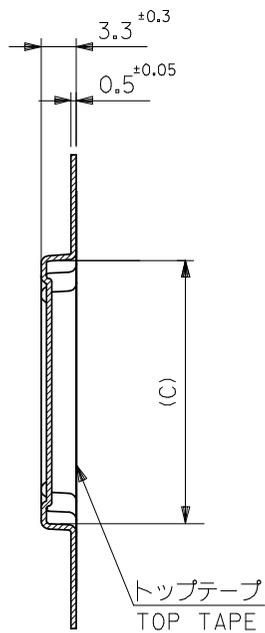
5. 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

6. 本製品は54132-**61に対するニッケルバリア品である。
THIS PRODUCT IS Ni-Barrier OF 54132-**61.



REVISED EC NO: J2008-4308 DRWN:WABEI 2008/06/27 CHKD:THARUYAMA 2008/06/30 APPR:NUKITA 2008/06/30	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER) molex MOLEX INCORPORATED			
		10 OVER 30 UNDER	± ---	CHECKED BY K.TOYODA	DATE 2004/09/27				
		30 OVER	± ---	APPROVED BY N.UKITA	DATE 2004/09/27				
		ANGULAR ± --- °		MATERIAL NO. SEE SHEET 4		DOCUMENT NO. SD-54132-064		SHEET NO. 3 OF 4	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
REV		SIZE A3							



44	49.4	45.4	30.8	31.9	26.1	29.6	54132-5062	50		
			28.3	29.4	23.6	27.1	54132-4562	45		
			27.3	28.4	22.6	26.1	54132-4362	43		
			25.8	26.9	21.1	24.6	54132-4062	40		
			24.8	25.9	20.1	23.6	54132-3862	38		
			23.8	24.9	19.1	22.6	54132-3662	36		
			23.3	24.4	18.6	22.1	54132-3562	35		
			22.8	23.9	18.1	21.6	54132-3462	34		
			22.3	23.4	17.6	21.1	54132-3362	33		
			21.8	22.9	17.1	20.6	54132-3262	32		
20.8	21.9	16.1	19.6	54132-3062	30					
キャリアテープ幅 CARRIER TAPE WIDTH			F	E	D	C	B	A	MATERIAL NO. (EMBOSS PKG)	CKT.

引き出し方向

SECT:Y-Y

トップテープ
TOP TAPE

CONNECTER
54132-xx68
**極数
KTC

SECT:X-X
(SCALE 5:1)

REVISED EC NO: J2008-4308 DRWN:MNABEI 2008/06/27 CHKD:THARUYAMA 2008/06/30 APPR:NUKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)			
	10 OVER 30 UNDER	± ---	CHECKED BY K.TOYODA	DATE 2004/09/27	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY M.UMEDA	DATE 2004/09/27	DOCUMENT NO. SD-54132-064		SHEET NO. 4 OF 4	
	ANGULAR	± --- °	MATERIAL NO. SEE TABLE					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					